the wafer has a peak-to-valley flatness less than about 1 μinch.

16. (Twice Amended) The wafer of claim 11 wherein the surface of the wafer has a surface flatness less than about 1 μinch.

17. (Twice Amended) The wafer of claim 11 wherein the array of glide transducers are mounted on a wafer surface opposite to the surface of the wafer having the air bearing surfaces formed thereon.

18. (Twice Amended) The wafer of claim 11 wherein the surface of the wafer has a flatness less than about 0.5 μinch.

19. (Twice Amended) A glide head formed from the a wafer comprising a plurality of rows and a plurality of columns of glide portions having a plurality of air bearing surfaces formed on a surface of the wafer and an array of glide transducers on the wafer and the glide head formed from one of said glide portions.

23. (Amended) The wafer of claim 11 wherein the array of glide transducers are formed on the surface of the wafer having the air bearing surfaces formed thereon.

25. (Amended) The wafer of claim 24 wherein the thermal transducers of the array of thermal transducers are formed of magnetoresistive sensors.

Please add new claim 26 as follows:

26. (New) The wafer of claim 11 wherein the air bearing surfaces of the plurality of rows and the plurality of columns of glide portions are formed using one of or a combination of saw cutting, milling or deposition techniques.